

## AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An apparatus comprising:  
a plurality of circuit substrates on a substrate and the plurality of circuit substrates are in a non-planar orientation relative to one another, each circuit substrate comprising a single crystal semiconductor layer having a smallest dimension reduced; with  
circuit devices formed in the single crystal layer.
2. (Canceled)
3. (Canceled)
4. (Previously Presented) The apparatus of claim 1, wherein the circuit devices form integrated circuits that interact with other electrical devices off the single crystal layer on which the integrated circuits are formed.
5. (Previously Presented) The apparatus of claim 1, wherein the smallest dimension of each circuit substrate comprises a thickness less than 100 microns.
6. (Previously Presented) The apparatus of claim 1, further comprising a dielectric material disposed between the adjacent ones of the plurality of circuit substrates.